

ABSTRACT

WAFER AND METHOD OF PROCESSING WAFER

A method of processing a wafer having on a face side thereof a device area with a plurality of devices formed therein and an outer circumferential excess area surrounding the device area includes a grinding step for grinding a reverse side of the wafer corresponding to the device area with a grinding wheel that is smaller in diameter than the wafer, thereby forming a first portion corresponding to the device area and an annular second portion surrounding the first portion, the annular second portion being thicker and more protrusive toward a reverse side thereof than the first portion. In the grinding step, the grinding wheel and the wafer are moved relatively to each other so that the angle formed between the reverse side of the first portion and an inner side surface of the annular second portion is larger than 45° and smaller than 75° .

(Figure 2A)